

板材信息 (参考)

板材 FR4		Typical (mil)	Unit
Solder Mask		0.7	mil
Copper Plated	0.5 oz	0.7	mil
Copper foil	0.5 oz	0.7	mil
PP	6.6mil	6.6	mil
Copper foil	1 oz	1.4	mil
Core (7628*5)	12 mil	12	mil
Copper foil	1 oz	1.4	mil
PP	6.6mil	6.6	mil
Copper foil	0.5 oz	0.7	mil
Copper Plated	0.5 oz	0.7	mil
Solder Mask		0.7	mil
Total Board Thickness		32.200	mil
Total Board Thickness		0.818	mm

阻抗线宽 (参考)

单端走线			
线宽(mil)	所在/参考层	ohm 值	仿真值
11(gap14mil)	L1/L2	50	50.02

